

48 I/O QFN Package Information

The package is a 48 plastic leadless chip carrier with a metal slug in the bottom to be used as an electrical ground connection and as a heat spreader. The θ_{ja} is

19 °C/W when the bottom metal slug is soldered to the PCB.

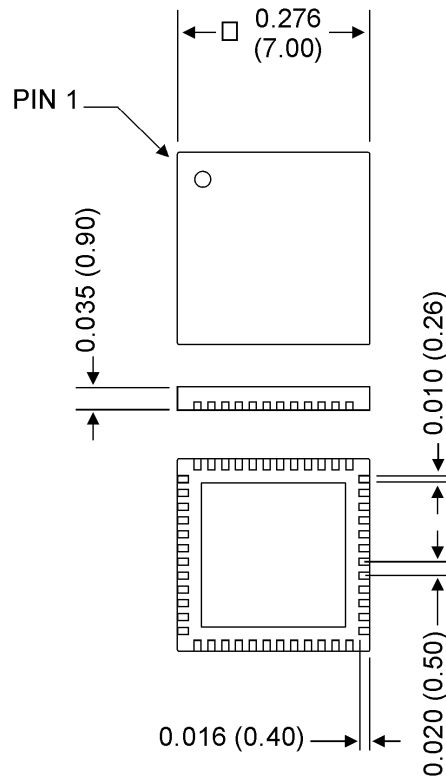


Figure 1. Package outline, dimensions in inches (mm).

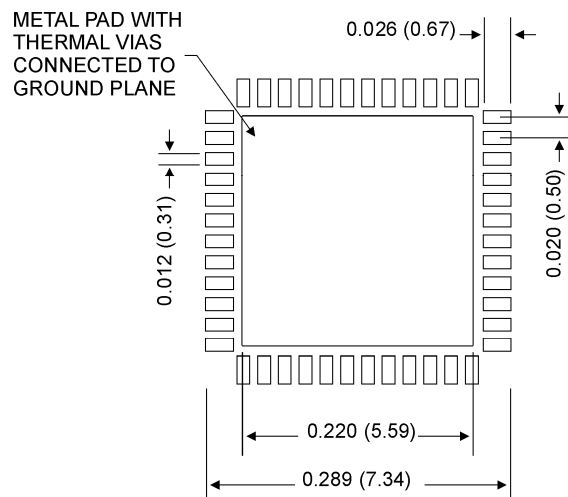


Figure 2. Footprint dimensions shown in inches (mm).